


NOTES: UNLESS OTHERWISE SPECIFIED.

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-810.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER SMD SIDES. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. MARK EACH ASSEMBLY TYPE WITH BLACK PERMANENT MARKER WHERE SHOWN. SEE BILL OF MATERIALS.

REVISION HISTORY			
ECO	REV	DESCRIPTION	APPROVAL DATE
	1	FIRST PROTOTYPE	Y1 S. 02/03/11

APPROVALS						1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1800 www.linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY	
PCB DES.	MI	TITLE: TOP ASSEMBLY DRAWING,		DUAL PHASE / DUAL OUTPUT SYNCHRONOUS			
APP. ENG.	YI S.	BUCK CONVERTER					
		SIZE	IC NO.	LTC3869EUFD	REV	1	
		N/A	DEMO CIRCUIT 1807A				
SCALE: NONE		FILENAME: 1807a-1.PCB			SHT 1 of 2		